



The ELPEPCB® HSP 801 S on a design board demonstrates the great layout flexibility of Peters' heatsink paste. Photo: Peters/Axel Küppers

## THE PETERS GROUP

Based in Kempen, Germany on the Lower Rhine, the Peters Group is and remains an independent family-owned company and the only full-range supplier of coating materials for electronics worldwide, in the field of printed circuit boards (PCBs) production as well as the protection of assembled PCBs and electronic components (EMS).

Our high-tech products developed and manufactured in Germany are used, amongst others, in e-mobility/the automotive industry, in industrial and plant engineering, aerospace, medical technology, the LED industry as well as for converters in renewable energy generators.

For over 50 years, our research and development team has been working closely with customers to develop innovative solutions. With its own international service and sales companies and around 65 sales partners, Peters is a well-known competent and reliable partner in over 90 countries serving more than 4,000 customers.

## Peters spotlights ELPEPCB® HSP 801 S at productronica

**Kempen, 22.10.25** – The ELPEPCB® HSP 801 S heatsink paste is considered a premium product for Peters when exhibiting at the upcoming productronica. At the world's leading trade fair for electronics development and manufacturing which will take place in Munich from November 18 to 21, 2025, the coatings manufacturer from Germany's Lower-Rhine Area will be presenting the system's high thermal conductivity of 3 W/mK to an international audience of experts. At booth B3-343 of the exhibition center located in Munich-Riem, Peters will recommend ELPEPCB® HSP 801 S with outstanding features as the latest in heatsink pastes for the thermal-management of printed circuit boards and flat assemblies.

### Great layout flexibility

The single-component epoxy-based heatsink paste for screen and stencil printing offers industrial users extensive layout flexibility. Besides its thermal conductivity and high glass transition temperature ( $T_g$  beyond 150° C), the heatsink paste distinguishes itself by a low thermal expansion coefficient and impressive dielectric strength (DC). The S in the brand ELPEPCB® HSP 801 S stands for low surface roughness, which enables optimal thermal coupling in combination with high thermal conductivity.

Further details on the performance of Peters heatsink paste will be explained by Sven Kramer in his presentation on the first day of the trade fair, 18 November, from 2 to 2.30 p.m. in Hall B3, not far from the Peters booth. This presentation held at the PCB & EMS Forum by the Global Manager of Application Technology is entitled "The Next Level – Successful Thermal Management with a New Generation of Printable Heatsinks".

*#Heatsinkpaste*

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